| ENVIRONMENTAL AND PACKAGE TESTING DATA FOR 1206-8 ChipFET® | | | | | |
|---|---|---|---|---|---|
| **Stress** | **Sample Size** | **Device Hr./Cyc** | **Condition** | **Total Fails** | **Fail Percentage** |
| BOND INT | 120 | 60,000 | 200°C + N2 | 0 | 0.00 |
| Pressure Pot | 165 | 15,840 | 121°, 15 PSIG | 0 | 0.00 |
| Solder DUNK | 185 | 555 | 260°C, 10SEC | 0 | 0.00 |
| Solderability | 15 | 120 | 883 M2003 | 0 | 0.00 |
| Temp Cycle | 320 | 187,500 | −65°C−150°C | 0 | 0.00 |